

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic				Symbol	Value	Units
Drain-Source Voltage				V _{DSS}	30	V
Gate-Source Voltage				V _{GSS}	±20	V
Continuous Drain Current (Note 5)	V _{GS} = 10V	Steady State	T _A = 25°C T _A = 70°C	I _D	260 200	mA
Continuous Drain Current (Note 5)	V _{GS} = 5V	Steady State	T _A = 25°C T _A = 70°C	I _D	220 160	mA
Pulsed Drain Current (10μs pulse, duty cycle = 1%)				I _{DM}	800	mA

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Units
Total Power Dissipation	(Note 5)	P _D	450	mW
Thermal Resistance, Junction to Ambient	(Note 5)	R _{θJA}	281	°C/W
Operating and Storage Temperature Range		T _J , T _{STG}	-55 to 150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 6)						
Drain-Source Breakdown Voltage	BV _{DSS}	30	—	—	V	V _{GS} = 0V, I _D = 250μA
Zero Gate Voltage Drain Current	I _{DSS}	—	—	1.0	μA	V _{DS} = 30V, V _{GS} = 0V
Gate-Body Leakage	I _{GSS}	—	—	±10.0	μA	V _{GS} = ±20V, V _{DS} = 0V
ON CHARACTERISTICS (Note 6)						
Gate Threshold Voltage	V _{GS(th)}	0.8	—	1.5	V	V _{DS} = V _{GS} , I _D = 250μA
Static Drain-Source On-Resistance	R _{DS(on)}	—	—	2.8	Ω	V _{GS} = 10.0V, I _D = 250mA
		—	—	3.8		V _{GS} = 5.0V, I _D = 250mA
		—	—	4.2		V _{GS} = 4.5V, I _D = 250mA
		—	—	4.5		V _{GS} = 4.0V, I _D = 250mA
		—	—	13		V _{GS} = 2.5V, I _D = 10mA
Forward Transconductance	g _{FS}	80	—	—	mS	V _{DS} = 10V, I _D = 0.115A
Diode Forward Voltage	V _{SD}	-	0.8	1.2	V	V _{GS} = 0V, I _S = 115mA
DYNAMIC CHARACTERISTICS (Note 7)						
Input Capacitance	C _{iss}	—	22.0	—	pF	V _{DS} = 25V, V _{GS} = 0V, f = 1.0MHz
Output Capacitance	C _{oss}	—	3.2	—		
Reverse Transfer Capacitance	C _{rss}	—	2.0	—		
Gate Resistance	R _G	—	79.9	—	Ω	V _{DS} = 0V, V _{GS} = 0V, f = 1.0MHz
Total Gate Charge V _{GS} = 10V	Q _g	—	0.87	—	nC	V _{GS} = 10V, V _{DS} = 30V, I _D = 150mA
Total Gate Charge V _{GS} = 4.5V	Q _g	—	0.43	—		
Gate-Source Charge	Q _{gs}	—	0.11	—		
Gate-Drain Charge	Q _{gd}	—	0.11	—	nC	V _{DD} = 30V, I _D = 0.115A, V _{GEN} = 10V, R _{GEN} = 25Ω
Turn-On Delay Time	t _{D(on)}	—	3.3	—		
Turn-On Rise Time	t _r	—	3.2	—		
Turn-Off Delay Time	t _{D(off)}	—	12.0	—		
Turn-Off Fall Time	t _f	—	6.3	—	nS	

- Notes:
- Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided.
 - Short duration pulse test used to minimize self-heating effect.
 - Guaranteed by design. Not subject to production testing.

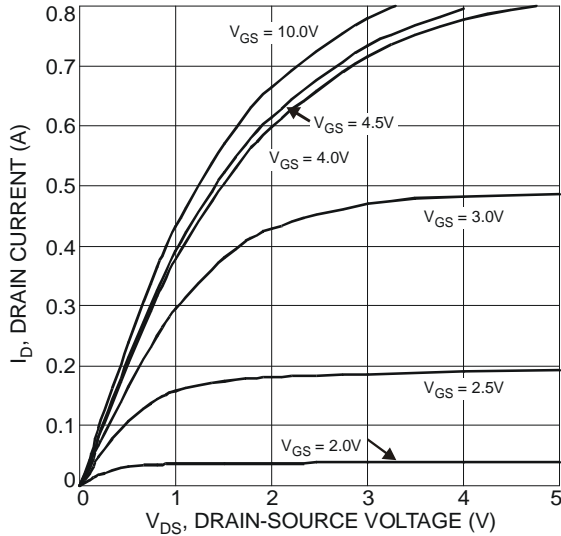


Figure 1 Typical Output Characteristic

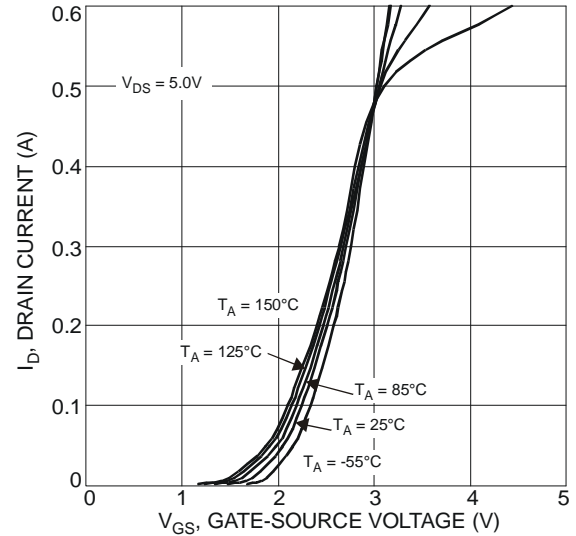


Figure 2 Typical Transfer Characteristics

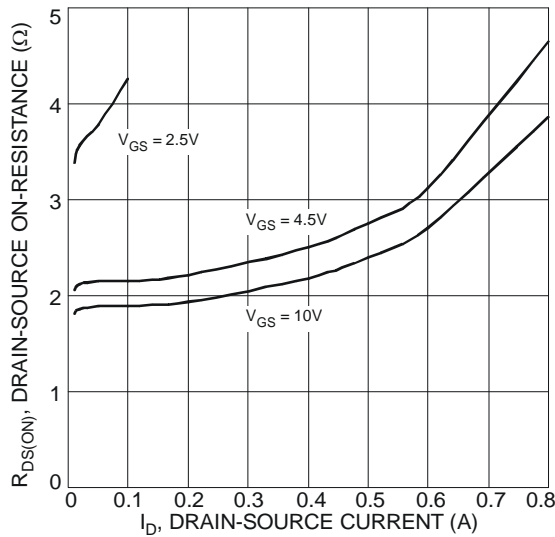


Figure 3 Typical On-Resistance vs. Drain Current and Gate Voltage

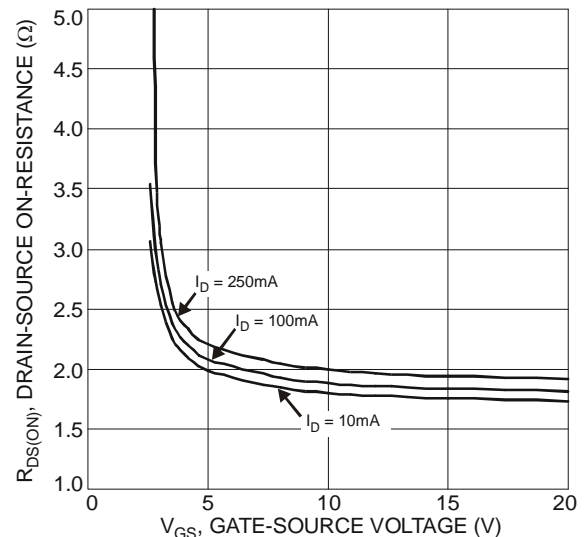


Figure 4 Typical Drain-Source On-Resistance vs. Gate-Source Voltage

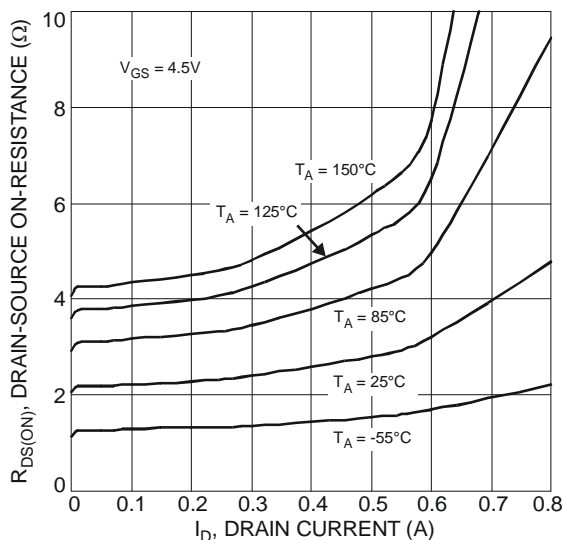


Figure 5 Typical On-Resistance vs. Drain Current and Temperature

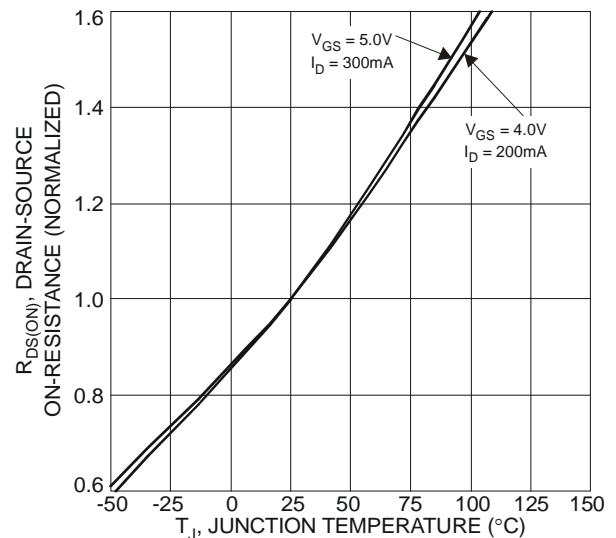


Figure 6 On-Resistance Variation with Temperature

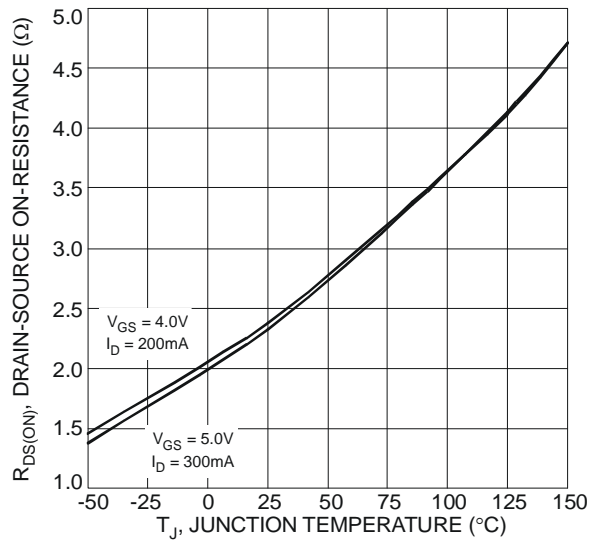


Figure 7 On-Resistance Variation with Temperature

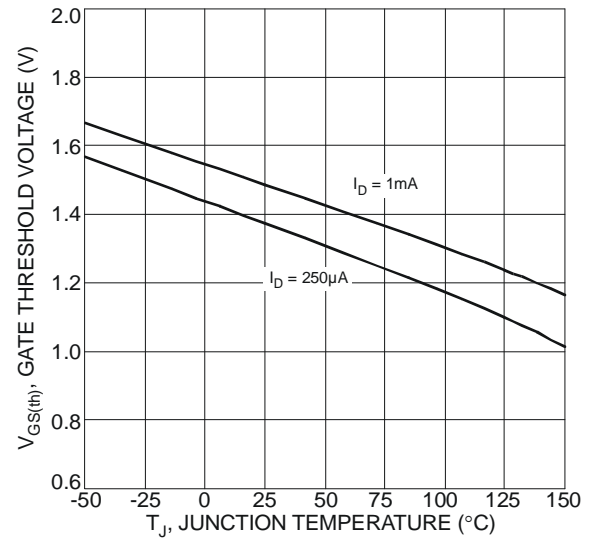


Figure 8 Gate Threshold Variation vs. Ambient Temperature

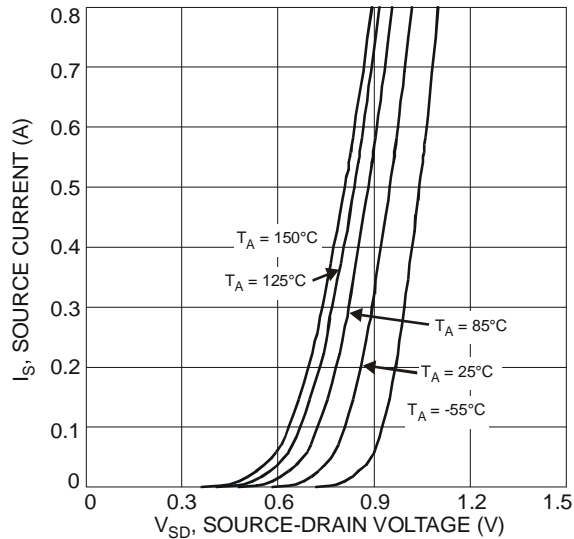
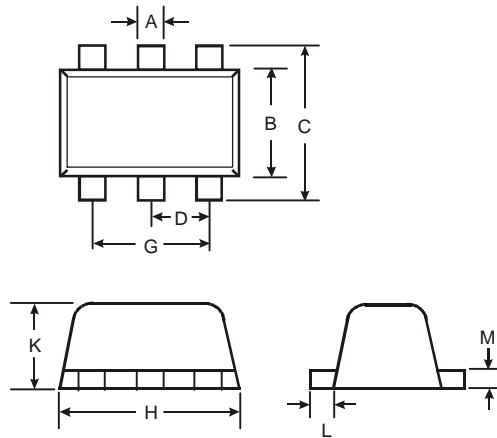


Figure 9 Diode Forward Voltage vs. Current

Package Outline Dimensions

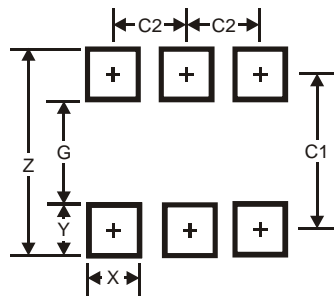
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.



SOT563			
Dim	Min	Max	Typ
A	0.15	0.30	0.20
B	1.10	1.25	1.20
C	1.55	1.70	1.60
D	-	-	0.50
G	0.90	1.10	1.00
H	1.50	1.70	1.60
K	0.55	0.60	0.60
L	0.10	0.30	0.20
M	0.10	0.18	0.11
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
Z	2.2
G	1.2
X	0.375
Y	0.5
C1	1.7
C2	0.5

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